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U.S. PTO
10020638

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10020638	FILING DATE 12/14/2001	CLASS 257	SUBCLASS 243	GAU 2811	EXAMINER 1027 Michael
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**APPLICANTS: Ma Bodan; Hong Sun; Tong Quinn;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 1979.EEM
Verified and Acknowledged Examiner's initials			
TITLE : Dual cure B-stageable underfill for wafer level			
U.S. DEPT. OF COMM./PAT & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Dwg.		<input type="checkbox"/> Figs.Dwg. <input checked="" type="checkbox"/> Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE Application Examiner		
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